

Thyristor \ Diode Module

= 2x 1200 V

85 A

 V_{T} 1.34 V

Phase leg

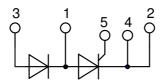
Part number

MCD72-12io1B



Backside: isolated





Features / Advantages:

- Thyristor for line frequency
- Planar passivated chip
- Long-term stability
- Direct Copper Bonded Al2O3-ceramic

Applications:

- Line rectifying 50/60 Hz
- Softstart AC motor control
- DC Motor control
- Power converter AC power control
- Lighting and temperature control

Package: TO-240AA

- Isolation Voltage: 3600 V~
- Industry standard outline
- RoHS compliant
- Soldering pins for PCB mounting
- Base plate: DCB ceramic
- · Reduced weight
- Advanced power cycling

Terms _Conditions of usage:

The data contained in this product data sheet is exclusively intended for technically trained staff. The user will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to his application. The specifications of our components may not be considered as an assurance of component characteristics. The information in the valid application- and assembly notes must be considered. Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of your product, please contact your local sales office.

Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact your local sales office.

Should you intend to use the product in aviation, in health or life endangering or life support applications, please notify. For any such application we urgently recommend

to perform joint risk and quality assessments;
the conclusion of quality agreements;

- to establish joint measures of an ongoing product survey, and that we may make delivery dependent on the realization of any such measures.

IXYS reserves the right to change limits, conditions and dimensions.

Data according to IEC 60747 and per semiconductor unless otherwise specified



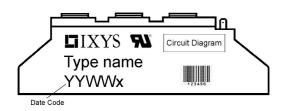
Rectifier		O a madistic man		Ì	Ratings		١
Symbol	Definition	Conditions	T 0500	min.	typ.	max.	Un
V _{RSM/DSM}	max. non-repetitive reverse/forwa		$T_{VJ} = 25^{\circ}C$			1300	ĺ
V _{RRM/DRM}	max. repetitive reverse/forward bl		$T_{VJ} = 25^{\circ}C$			1200	<u> </u>
I _{R/D}	reverse current, drain current	$V_{R/D} = 1200 \text{ V}$	$T_{VJ} = 25^{\circ}C$			200	μ
		$V_{R/D} = 1200 \text{ V}$	$T_{VJ} = 125^{\circ}C$			5	m
V _T	forward voltage drop	$I_T = 150 A$	$T_{VJ} = 25^{\circ}C$			1.34	,
		$I_{T} = 300 \text{ A}$				1.74	'
		$I_{T} = 150 \text{ A}$	$T_{VJ} = 125$ °C			1.34	,
		$I_{T} = 300 \text{ A}$				1.82	! !
I _{TAV}	average forward current	$T_{C} = 85^{\circ}C$	$T_{VJ} = 125$ °C			85	
I _{T(RMS)}	RMS forward current	180° sine				133	
V _{T0}	threshold voltage		T _{vJ} = 125°C			0.85	,
r _T	slope resistance	oss calculation only				3.2	m۵
R _{thJC}	thermal resistance junction to cas	e				0.3	K/V
R _{thCH}	thermal resistance case to heatsi	nk			0.20		K/V
P _{tot}	total power dissipation		T _C = 25°C			333	٧
I _{TSM}	max. forward surge current	t = 10 ms; (50 Hz), sine	T _{v.1} = 45°C			1.70	k,
1011	-	t = 8,3 ms; (60 Hz), sine	$V_R = 0 V$			1.84	k,
		t = 10 ms; (50 Hz), sine	T _{v.i} = 125°C			1.45	k
		t = 8.3 ms; (60 Hz), sine	$V_R = 0 V$			1.56	k
l²t	value for fusing	t = 10 ms; (50 Hz), sine	$T_{VJ} = 45^{\circ}C$				kA ²
	Tanas is isomig	t = 8.3 ms; (60 Hz), sine	$V_R = 0 V$			14.0	i
		t = 0.5 ms; (50 Hz), sine	$T_{VJ} = 125^{\circ}C$			10.4	į .
		t = 8.3 ms; (60 Hz), sine	$V_R = 0 V$			10.1	į.
C _J	junction capacitance	$V_{R} = 400 \text{ V} \text{ f} = 1 \text{ MHz}$	$T_{VJ} = 25^{\circ}C$		119	10.1	pl
		$t_{P} = 30 \mu s$	$T_{\rm C} = 125^{\circ}{\rm C}$		113	10	V
P _{GM}	max. gate power dissipation	·	1 _C = 123 U			5	۷
D		t _P = 300 μs				_	ļ.
P _{GAV}	average gate power dissipation	T 40500 (5011	1'1' L 050 A			0.5	V
(di/dt) _{cr}	critical rate of rise of current	$T_{VJ} = 125 ^{\circ}\text{C}; f = 50 \text{Hz}$	•			150	Α/μ
		$t_P = 200 \mu\text{s}; di_G/dt = 0.45 A/\mu\text{s}; -$					
			on-repet., $I_T = 85 A$				A/μ
(dv/dt) _{cr}	critical rate of rise of voltage	$V = \frac{2}{3} V_{DRM}$	$T_{VJ} = 125^{\circ}C$			1000	V/μ
		R _{GK} = ∞; method 1 (linear volta					! ! ! !
V_{GT}	gate trigger voltage	$V_D = 6 V$	$T_{VJ} = 25^{\circ}C$			2.5	١
			$T_{VJ} = -40$ °C			2.6	١
I _{GT}	gate trigger current	$V_D = 6 V$	$T_{VJ} = 25^{\circ}C$			150	m
			$T_{VJ} = -40$ °C			200	m
$V_{\sf GD}$	gate non-trigger voltage	$V_D = \frac{2}{3} V_{DRM}$	$T_{VJ} = 125^{\circ}C$			0.2	١
I _{GD}	gate non-trigger current					10	m
I _L	latching current	t _p = 10 μs	T _{VJ} = 25°C			450	m
_		$I_{G} = 0.45 \text{ A}; \text{ di}_{G}/\text{dt} = 0.45 \text{ A}/\mu\text{s}$	3				1 1 1
I _H	holding current	$V_D = 6 \text{ V } R_{GK} = \infty$	T _{vJ} = 25°C			200	m
t _{gd}	gate controlled delay time	$V_D = \frac{1}{2} V_{DRM}$	$T_{VJ} = 25$ °C			2	μ
	- , , , , , , , , , , , , , , , , , , ,					_	٣
gu		$I_0 = 0.45 A$, $\Omega I_0/\Omega I = 0.45 A/\Omega I_0$					
t _q	turn-off time	$I_G = 0.45 \text{ A}; \text{ di}_G/\text{dt} = 0.45 \text{ A}/\mu\text{s}$ $V_B = 100 \text{ V}; I_T = 150 \text{ A}; V = \frac{2}{3}$			185		μ

IXYS reserves the right to change limits, conditions and dimensions.

Data according to IEC 60747and per semiconductor unless otherwise specified



Package	Package TO-240AA			Ratings				
Symbol	Definition	Conditions			min.	typ.	max.	Unit
RMS	RMS current	per terminal					200	Α
T _{vJ}	virtual junction temperature				-40		125	°C
T _{op}	operation temperature				-40		100	°C
T _{stg}	storage temperature				-40		125	°C
Weight						81		g
M _D	mounting torque				2.5		4	Nm
$\mathbf{M}_{_{T}}$	terminal torque				2.5		4	Nm
d _{Spp/App}	oroopaga distance on surface	terminal to terminal 13.0 creepage distance on surface striking distance through air		9.7			mm	
$d_{\text{Spb/Apb}}$	creepage distance on surface	Striking distance through an	terminal to backside 16.0		16.0			mm
V _{ISOL}	isolation voltage	t = 1 second	50/60 Hz. RMS: IISOL ≤ 1 mA		3600			٧
.002		t = 1 minute			3000			٧



Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	MCD72-12io1B	MCD72-12io1B	Box	36	469475

Similar Part	Package	Voltage class
MCMA85PD1200TB	TO-240AA-1B	1200
MCMA110PD1200TB	TO-240AA-1B	1200

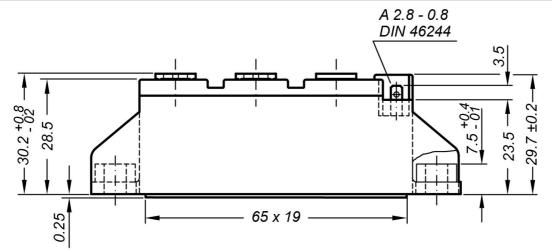
Equiva	alent Circuits for	Simulation	* on die level	T _{vJ} = 125 °C
$I \rightarrow V_0$)— <u>R</u> o	Thyristor		
V _{0 max}	threshold voltage	0.85		V
$R_{0 \text{ max}}$	slope resistance *	2		mΩ

IXYS reserves the right to change limits, conditions and dimensions.

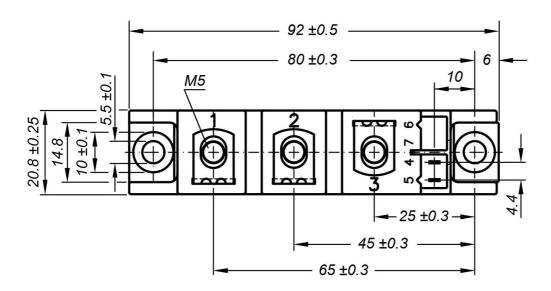
Data according to IEC 60747and per semiconductor unless otherwise specified



Outlines TO-240AA

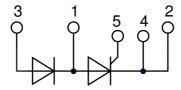


General tolerance: DIN ISO 2768 class "c"



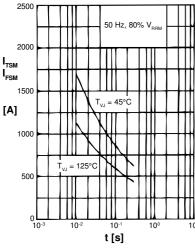
Optional accessories: Keyed gate/cathode twin plugs Wire length: 350 mm, gate = white, cathode = red UL 758, style 3751

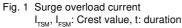
Type **ZY 200L** (L = Left for pin pair 4/5)





Thyristor





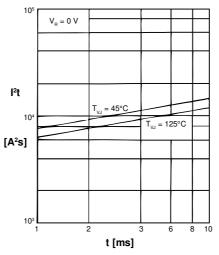


Fig. 2 I2t versus time (1-10 ms)

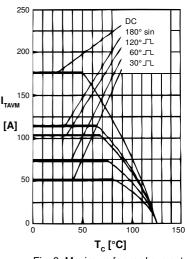


Fig. 3 Maximum forward current at case temperature

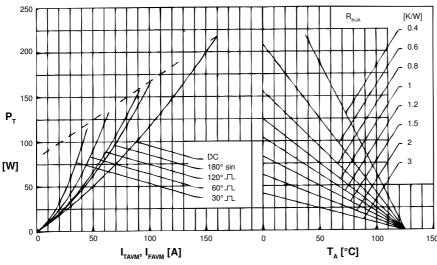


Fig. 4 Power dissipation vs. onstate current and ambient temperature (per thyristor/diode)

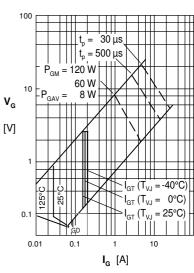


Fig. 5 Gate trigger characteristics

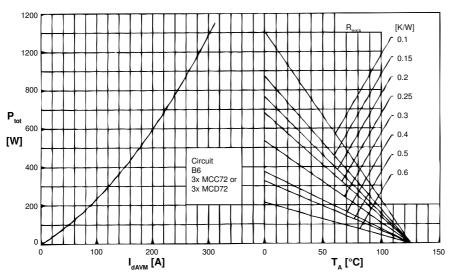


Fig. 6 Three phase rectifier bridge: Power dissipation versus direct output current and ambient temperature

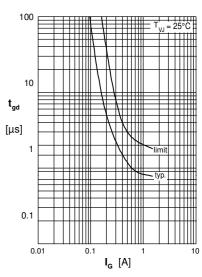


Fig. 7 Gate trigger delay time

IXYS reserves the right to change limits, conditions and dimensions

Data according to IEC 60747and per semiconductor unless otherwise specified



Rectifier

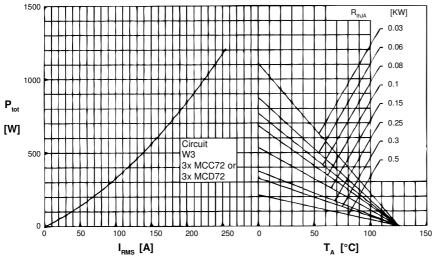


Fig. 8 Three phase AC-controller: Power dissipation versus RMS output current and ambient temperature

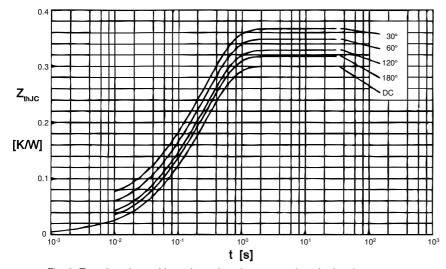
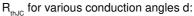


Fig. 9 Transient thermal impedance junction to case (per thyristor)



thJC	a
d	R_{thJC} [K/W]
DC	0.30
180°	0.31
120°	0.33
60°	0.35
30°	0.37

Constants for $Z_{\mbox{\tiny thJC}}$ calculation:

i F	R _{thi} [K/W]	t _, [s]
1	0.008	0.0019
2	0.054	0.0470
3	0.238	0.3000

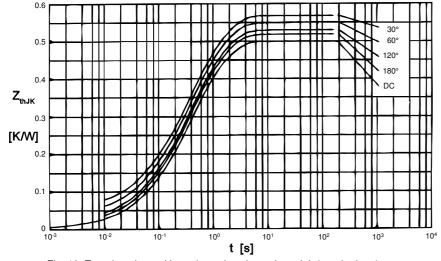


Fig. 10 Transient thermal impedance junction to heatsink (per thyristor)

 $\boldsymbol{R}_{\text{\tiny thJK}}$ for various conduction angles d:

thJK 101 V	anous conac
d	R_{thJK} [K/W]
DC	0.50
180°	0.51
120°	0.53
60°	0.55
30°	0.57

Constants for Z_{thJK} calculation:

i	R _{thi} [K/W]	t, [s]
1	0.008	0.0019
2	0.054	0.0470
3	0.238	0.3000
4	0.200	1.2500

IXYS reserves the right to change limits, conditions and dimensions.

Data according to IEC 60747and per semiconductor unless otherwise specified